

FEATURES AND SPECIFICATIONS

Features and Benefits

- Stacking height: 2.0mm
- Sizes 40 to 80 circuits
- High temperature housing
- Durable blade on beam contact interface
- Anti-flux design

Reference Information

Packaging: Embossed tape

Mates With: [53729](#)

Designed In: Millimeters

Electrical

Voltage: 50V

Current: 0.5A

Contact Resistance: 30mΩ max.

Dielectric Withstanding Voltage: 500V AC

Insulation Resistance: 500 MΩ min.

Physical

Housing: White glass-filled LCP, UL 94V-0

Contact: Phosphor Bronze

Vacuum Pick-Up Tape: Polyimide

Plating: Gold over nickel

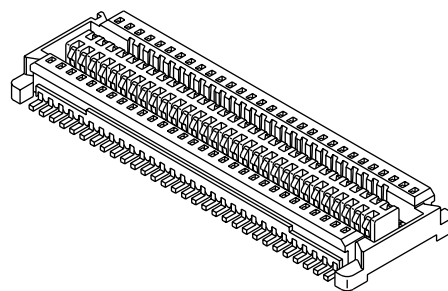
Operating Temperature: -40 to +105°C



0.50mm (.020") Pitch Board-to-Board Receptacle

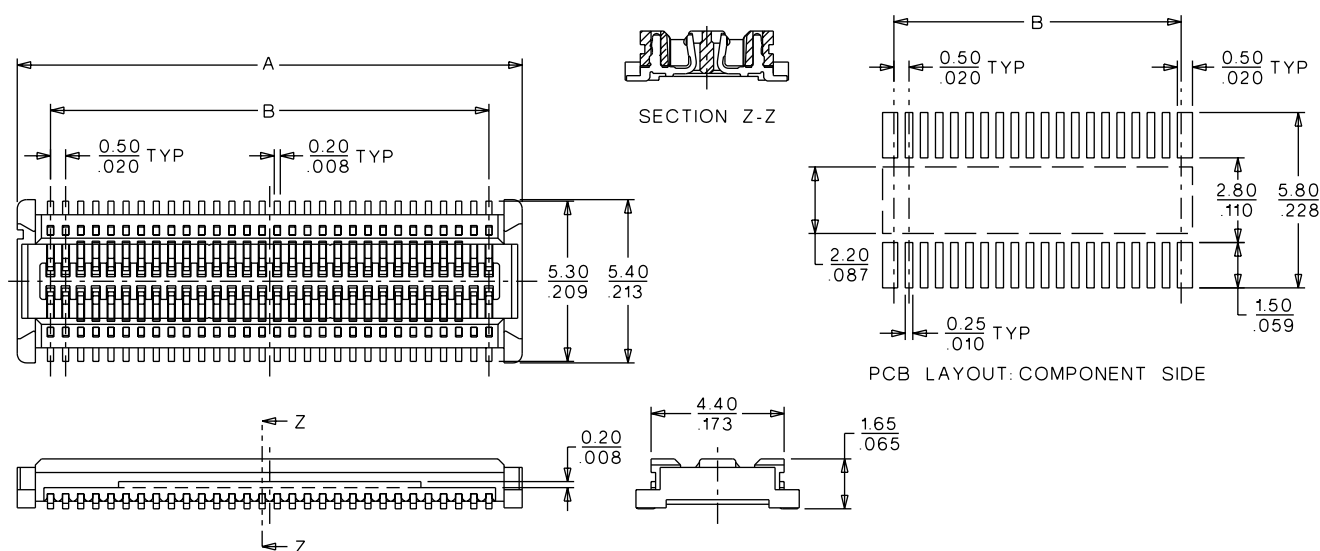
52974

**SMT, Dual Row
Vertical Stacking**



0.40 to 1.60mm (.016 to .063") Pitch

CATALOG DRAWING (FOR REFERENCE ONLY)



ORDERING INFORMATION AND DIMENSIONS

Circuits	Order No.		Dimension		Carrier Tape Width
	With Vacuum Pick-Up Tape	Without Vacuum Pick-Up Tape	A	B	
40	52974-0404	52974-0408	11.70 (.460)	9.50 (.374)	24.00 (.945)
50	52974-0504	52974-0508	14.20 (.559)	12.00 (.472)	24.00 (.945)
60	52974-0604	52974-0608	16.70 (.657)	14.50 (.570)	24.00 (.945)
80	52974-0804	52974-0808	21.70 (.854)	19.50 (.767)	32.00 (1.260)

Note: Contact Molex for embossed tape specifications

Note: Use only one connector per daughterboard in order to insure proper mating alignment